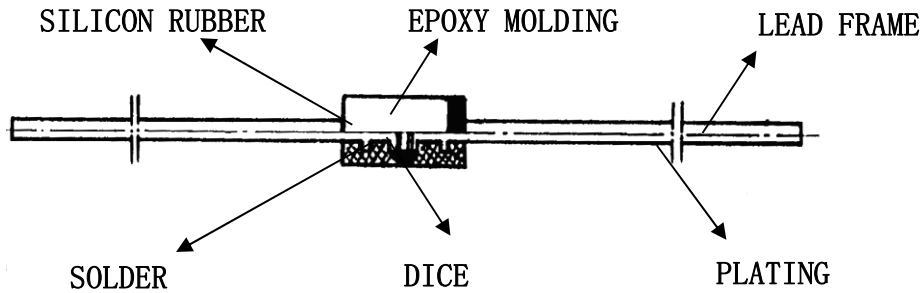




Chemical Composition of Diode products (Lead Free)



DO-41:

(Weight: 280mg / pcs)

Make up of material	Chemical Composition	CAS No.	Substance Weight (mg)	Content (%)
Plating(5.757mg)	Sn	7440-31-5	5.7552729	2.055
	Others	---	0.0017271	0.001
Solder (0.5mg)	Pb	7439-92-1	0.4625	0.165
	Ag	7440-22-4	0.025	0.009
	Cu	7440-50-8	0.0125	0.004
Epoxy Molding (98.4mg)	Crystalline Silica (Quartz)	14808-60-7	75.041	26.800
	Cristobalite	14464-46-1	0.994	0.355
	Epoxy Resin	129915-35-1	10.934	3.905
	Phenol Resin	26834-02-6	9.94	3.550
	Carbon Black	1333-86-4	0.497	0.178
	Antimony ioxide Sb2O3	1309-64-4	0.994	0.355
Lead Frame (173.59mg)	Cu	7440-50-8	173.59	61.996
Dice (0.693mg)	Si	7440-21-3	0.629244	0.225
	P	7723-14-0	0.017325	0.006
	Ni	7440-02-0	0.03465	0.012
	Be	7440-41-7	0.011781	0.004
Silicon rubber (1mg)	Si	7440-21-3	1	0.357
Ink (0.06mg)	C	7440-44-0	0.06	0.021

280

100.00

Remark: Pb is exemption used for high temperature Soldering.

Approved by: 劉偉

Prepared by: 林欣